

Patent Abstracts of Japan

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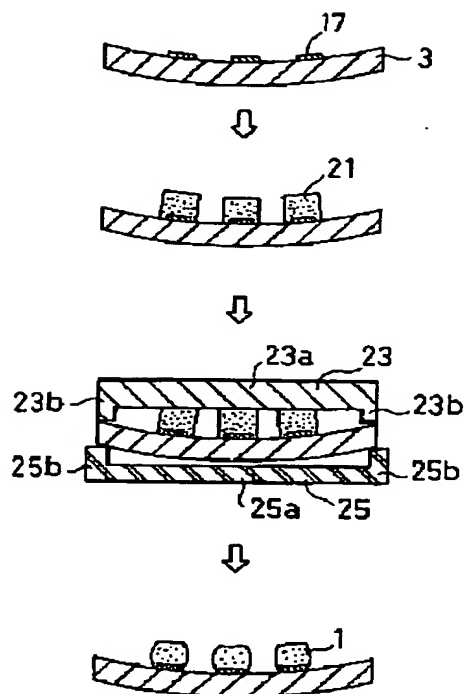
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TITLE : PRODUCTION OF WIRING BOARD
HAVING SOLDER BUMP AND
HOLDING JIG



ABSTRACT : PROBLEM TO BE SOLVED: To provide a method for producing a wiring board having a solder bump and a holding jig which can make coplanarity low and improve joint property as well as prevent the generation of solder bridges.

SOLUTION: A leveling jig 23 is provided in the front side of a wiring board 3 to regulate the height of a solder bump 1. The jig 23 consists of a plate flat part 23a and a leg part 23b. In addition, a holding jig 25 is provided in the rear side of the board 3 to hold both right and left ends of the board 3 so that the warpage of the board 3 can be prevented. The jig 25 is provided with a projecting holding part 25b for holding the board 23 on both ends of a plate flat part 25a. In this state, the board 3 is allowed to pass through a reflow furnace to melt a eutectic solder on the front side and it is cooled thereafter. Thus, the solder bump 1 whose top part is flattened is formed on the front side of the board 3.

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